

**Amendments to the Specification:**

Please replace the paragraph on page 14, line 17, to page 15, line 4, with the following paragraph:

In accordance with an added feature of the invention, the layer thickness of the semiconductor body has a specific sheet charge density  $[\rho]$   $\rho_F$  in a direction  $z$  between the pn junction and the second main surface such that:

$$\int_0^W \rho_F(z) dz \leq 0.9 Q_c, \quad \rho_F = \int \rho dF$$

in which  $\rho$  is the volume charge density,  $Q_c$ , the critical breakdown charge, denotes a critical value of the charge quantity  $Q$  at which the electrical breakdown is reached, said charge quantity  $Q$  being linked to said electric field strength  $E$  between said first electrode and said second electrode by the equations

$$\int_0^W \rho_F(z) dz = Q \text{ and Poisson's equation } \cancel{\nabla E = -4\pi\rho} \quad \underline{\nabla E = 4\pi\rho}.$$

Please replace the paragraph on page 20, line 4, to page 20, line 23, with the following paragraph:

The critical value  $E_c$  of the field strength is linked to a charge density  $\rho$  by Poisson's equation

$$\vec{\nabla} \cdot \vec{E} = -4\pi\rho \quad \vec{\nabla} \cdot \vec{E} = 4\pi\rho, \quad (1)$$

so that a relationship with a critical breakdown surface charge  $Q_c$  can be derived:

$$\int_0^{W_{sc}} \rho_F(z) dz \leq Q_c \quad (2)$$

$W_{sc}$  denotes the width of the space charge region (i.e. the region with  $|\vec{E}| \neq 0$ ) when the electric field reaches the critical field strength  $E_c$ . According to the invention, the layer thickness  $W$  should then be selected in such a way that the space charge zone reaches the second main surface 3 before the field strength takes on the critical value  $E_c$ . In this case, the integration in following equation (3) has to be carried out over the entire layer thickness  $W$  of the semiconductor body 1 between the pn-junction between the semiconductor body 1 and the body zone 4 and the second semiconductor surface 3. In other words, the integral in Equation (2) should, for example, reach at most the value  $0.9 Q_c$  so that, in the vertically structured power semiconductor component according to the invention, the following equation is satisfied:

$$\int_0^W \rho_F(z) dz \leq 0.9 Q_c, \quad \rho_F = \int \rho dF. \quad (3)$$